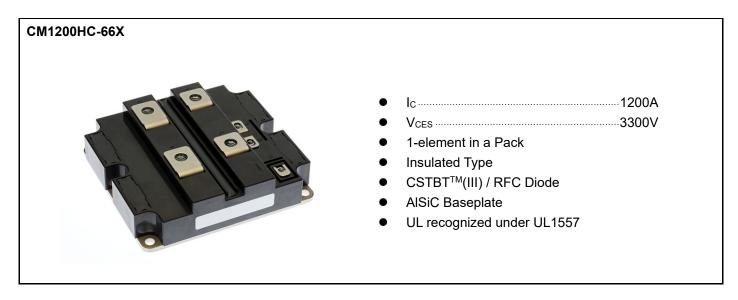


< High Voltage Insulated Gate Bipolar Transistor : HVIGBT >

CM1200HC-66X

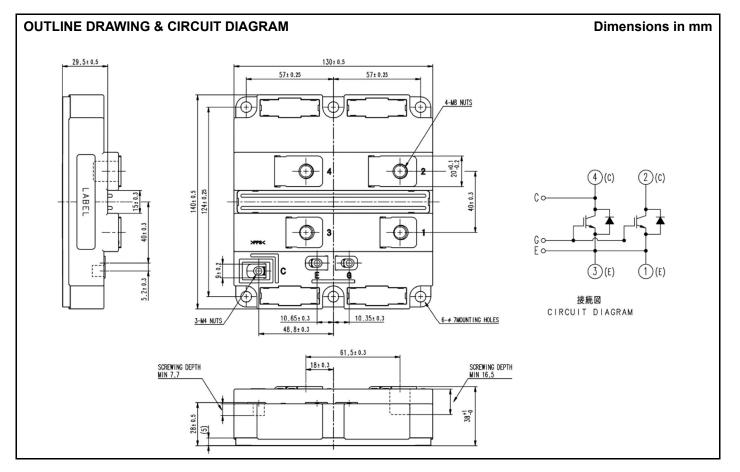
HIGH POWER SWITCHING USE INSULATED TYPE

5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules



APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers



< High Voltage Insulated Gate Bipolar Transistor: HVIGBT > CM1200HC-66X HIGH POWER SWITCHING USE INSULATED TYPE 5th-Version HVIGBT (High V

5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

MAXIMUM RATINGS

Symbol	Item	Conditions	Ratings	Unit
Mana	Collector-emitter voltage	V _{GE} = 0V, T _j = -40+150°C	3300	V
V _{CES}		$V_{GE} = 0V, T_j = -50^{\circ}C$	3200	v
V _{GES}	Gate-emitter voltage	$V_{CE} = 0V, T_j = 25^{\circ}C$	±20	V
lc	Callester evenent	DC, T _c = 105°C	1200	Α
ICRM	Collector current	Pulse (Note1)	2400	Α
IE	Funciation and and (Note2)	DC, T _c = 90°C	1200	Α
IERM	Emitter current ^(Note2)	Pulse (Note1)	2400	Α
Ptot	Maximum power dissipation (Note3)	T₀ = 25°C, IGBT part	11900	W
Viso	Isolation voltage	RMS, sinusoidal, f = 60Hz, t = 1 min.	6000	V
Ve	Partial discharge extinction voltage	RMS, sinusoidal, f = 60Hz, Q _{PD} ≤ 10pC	2600	V
Tj	Junction temperature		-50 ~ +150	°C
Tjop	Operating junction temperature		-50 ~ +150	°C
T _{stg}	Storage temperature		-55 ~ +150	°C
t _{psc}	Short circuit pulse width	V _{CC} = 2500V, V _{CE} ≤ V _{CES} , V _{GE} =15V, T _j =150°C	10	μs

ELECTRICAL CHARACTERISTICS

Sumbol	ltem	Conditions		Limits			Unit
Symbol	item	Conditions	Conditions		Тур	Max	Unit
			T _j = 25°C	_	_	4.0	
ICES	Collector cutoff current	V _{CE} = V _{CES} , V _{GE} = 0V	T _j = 125°C	_	4.0		mA
			T _j = 150°C	_	24.0		-
V _{GE(th)}	Gate-emitter threshold voltage	V _{CE} = 10V, I _C = 120mA, T _j = 25°C	•	6.5	7.0	7.5	V
Iges	Gate leakage current	$V_{GE} = V_{GES}, V_{CE} = 0V, T_j = 25^{\circ}C$		-0.5		0.5	μA
Cies	Input capacitance	(1 - 10)(1) = 0(1 + 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 - 100)(1 -		—	139	—	
Coes	Output capacitance	 V_{CE} = 10V, V_{GE} = 0V, f = 100kHz T_i = 25°C 			9.3	—	nF
Cres	Reverse transfer capacitance	- 1j - 25 C			1.3		
Q _G	Total gate charge	V _{CC} = 1800V, I _C = 1200A, V _{GE} = ±	=15V		9.0	—	μC
			T _j = 25°C	_	2.00		
V _{CEsat}	Collector-emitter saturation	$I_{\rm C} = 1200 {\rm A}^{({\rm Note4})}$	T _j = 125°C	—	2.50	—	V
	voltage	V _{GE} = 15V	T _i = 150°C	—	2.60	3.10	
t _{d(on)}	Turn-on delay time		T _i = 150°C	—	—	0.90	μs
tr	Rise time	Vcc = 1800V	T _i = 150°C	—	—	0.50	μs
	Turn-on switching energy	$I_{\rm c} = 1200 {\rm A}$	T _i = 25°C	—	1.95	—	J
E _{on(10%)}		$V_{GE} = \pm 15V$ $R_{G(on)} = 2.2\Omega$ $L_s = 150nH$ Inductive load	T _i = 125°C	—	2.15	_	
. ,	per pulse (Note5)		T _i = 150°C	—	2.25	_	
	Turn-on switching energy per pulse ^(Note6)		T _j = 25°C	—	2.00	—	J
Eon			T _i = 125°C	—	2.25	—	
			T _i = 150°C	—	2.35	—	
			T _i = 25°C	—	2.90	_	
t _{d(off)}	Turn-off delay time		T _i = 125°C	—	3.20	—	μs
			T _i = 150°C	—	3.20	4.25	
	Fall time	$V_{CC} = 1800V$ $I_C = 1200A$ $V_{GE} = \pm 15V$	T _i = 25°C	_	0.40	_	
t _f			T _i = 125°C	—	0.45	—	μs
			T _i = 150°C	_	0.50	1.00	
E _{off(10%)}	Turn-off switching energy	$R_{G(off)} = 18\Omega$	T _i = 25°C	—	1.55	_	
		L _s = 150nH	T _j = 125°C	—	2.00	_	J
``´´	per pulse (Note5)	Inductive load	T _i = 150°C	_	2.05	_	
		1	T _i = 25°C	—	1.65	_	
E _{off}	Turn-off switching energy per pulse (Note6)		T _i = 125°C	_	2.10		J
			T _i = 150°C	_	2.25		1

< High Voltage Insulated Gate Bipolar Transistor: HVIGBT > CM1200HC-66X HIGH POWER SWITCHING USE INSULATED TYPE 5th-Version HVIGBT (High V

5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

ELECTRICAL CHARACTERISTICS

Symbol	Item	Conditions		Limits			Unit
Symbol	item	Conditions			Тур	Max	Unit
		IE = 1200A (Note 4)	T _j = 25°C	—	2.20	_	
VEC	Emitter-collector voltage (Note 2)		T _j = 125°C	—	2.40		V
		$V_{GE} = 0V$	T _j = 150°C	—	2.50	3.00	
			T _j = 25°C	—	0.95	_	
trr	Reverse recovery time (Note 2)		T _j = 125°C	_	1.10	_	μs
			T _j = 150°C	—	1.15	_	
			T _j = 25°C	—	_	_	
Irr	Reverse recovery current (Note 2)		T _j = 125°C	—	1550		А
			T _j = 150°C		1650		
	Reverse recovery charge (Note 2,7)	V _{CC} = 1800V	T _j = 25°C	—	1050		
Qrr(10%)		$I_{E} = 1200A$ $V_{GE} = \pm 15V$ $R_{G(on)} = 2.2\Omega$	T _j = 125°C	—	1600		μC
			T _j = 150°C	—	1650	_	
			T _j = 25°C	—	1200		
Qrr	Reverse recovery charge (Note 2,6)	L _s = 150nH	T _j = 125°C	—	1750	_	μC
		Inductive load	T _j = 150°C		1800		
	D	7	T _j = 25°C	—	1.15		
Erec(10%)	Reverse recovery energy per pulse (Note 2,5)		T _j = 125°C	—	1.65	_	J
			T _j = 150°C		1.85		
	Reverse recovery energy per pulse (Note 2,6)		T _j = 25°C	_	1.25		
Erec			T _j = 125°C		1.75	_	J
			T _j = 150°C		1.95	_	

THERMAL CHARACTERISTICS

Sympol	Item	Conditions	Limits			Unit
Symbol			Min	Тур	Max	Unit
R _{th(j-c)Q}	Thermal resistance	Junction to Case, IGBT part		—	10.5	K/kW
R _{th(j-c)D}	Thermarresistance	Junction to Case, FWDi part		_	16.5	K/kW
R _{th(c-s)}	Contact thermal resistance	Case to heat sink $\lambda_{grease} = 1W/m \cdot k$, $D_{(c-s)} = 80 \mu m$	_	7.5	_	K/kW

MECHANICAL CHARACTERISTICS

Symbol	ltem	Conditions		Limits		
		Conditions	Min	Тур	Max	Unit
Mt	Mounting torque	M8 : Main terminals screw	7.0	_	19.0	N∙m
Ms	Mounting torque	M6 : Mounting screw	3.0	—	6.0	N∙m
Mt	Mounting torque (Note 8)	M4 : Auxiliary terminals screw	1.0	_	3.0	N∙m
Μ	Mass		—	0.9	—	kg
CTI	Comparative tracking index		600	—	—	—
da	Clearance		19.5	—	—	mm
ds	Creepage distance		32.0	—	—	mm
Lp ce	Parasitic stray inductance		_	12.0	—	nH
R _{CC'+EE'}	Internal lead resistance	$T_c = 25^{\circ}C$	—	0.14	—	mΩ

Note 1: Pulse width and repetition rate should be such that junction temperature (T_j) does not exceed T_{jopmax} rating.

Note 2: The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).

Note 3: Junction temperature (T_j) should not exceed T_{jmax} rating (150°C).

Note 4: Pulse width and repetition rate should be such as to cause negligible temperature rise.

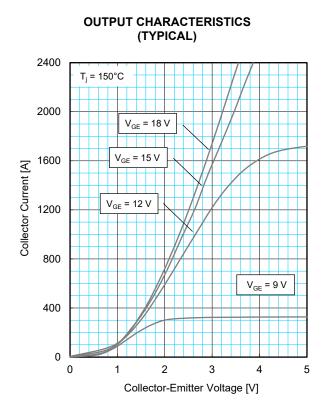
Note 5: The integration range of switching energies is from $10\%V_{CE}$ to $10\%I_{C}(10\%I_{E})$.

Note 6: Definition of all items is according to IEC 60747, unless otherwise specified.

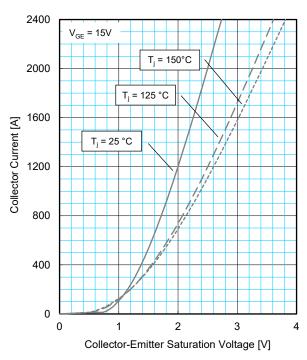
Note 7: The integration range of reverse recovery charge is from $I_E = 0A$ to $10\% I_E$.

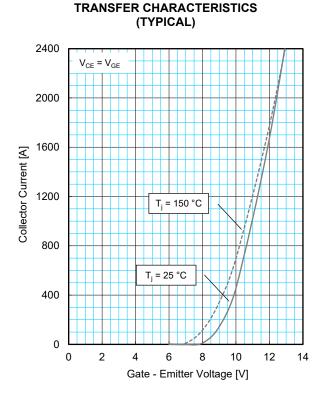
Note 8: The maximum specified value is under the condition of using PCB mounted on the power module.

In case no PCB is used this maximum torque for M4 screw is 1.9 N·m.

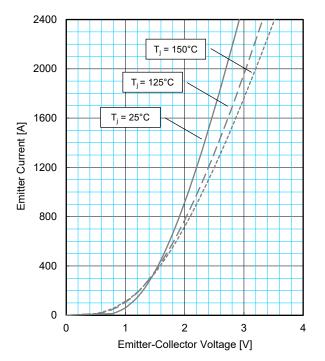


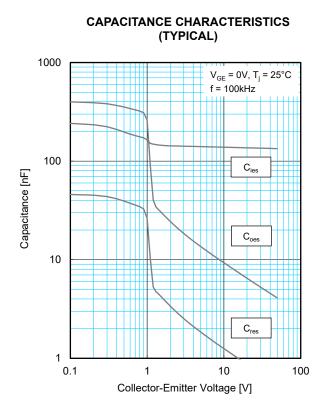


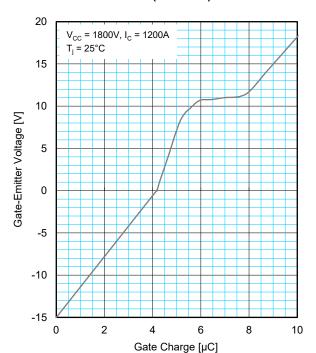




FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)

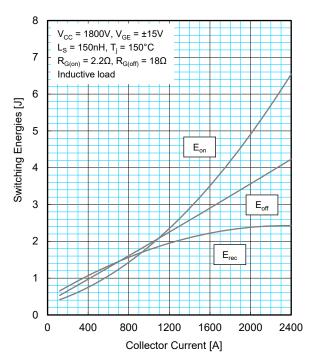




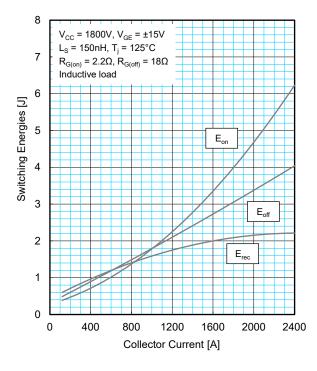


GATE CHARGE CHARACTERISTICS (TYPICAL)

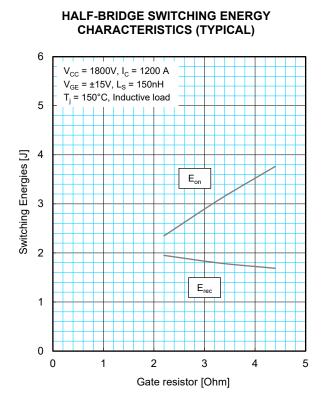
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)







Dec. 2022 (HVM-1083-H)

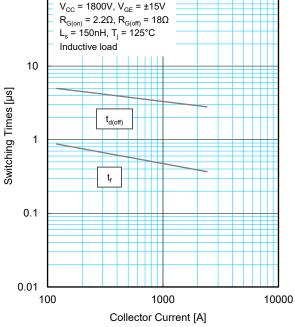


6 $V_{\rm CC}$ = 1800V, $I_{\rm C}$ = 1200 A $V_{GE} = \pm 15V, L_{S} = 150nH$ $T_i = 150^{\circ}C$, Inductive load 5 Switching Energies [J] 4 3 2 $\mathsf{E}_{\mathsf{off}}$ 1 0 0 10 20 30 40 Gate resistor [Ohm]

HALF-BRIDGE SWITCHING ENERGY

CHARACTERISTICS (TYPICAL)

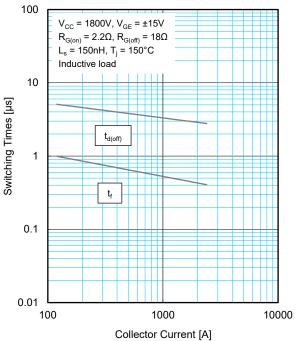
10



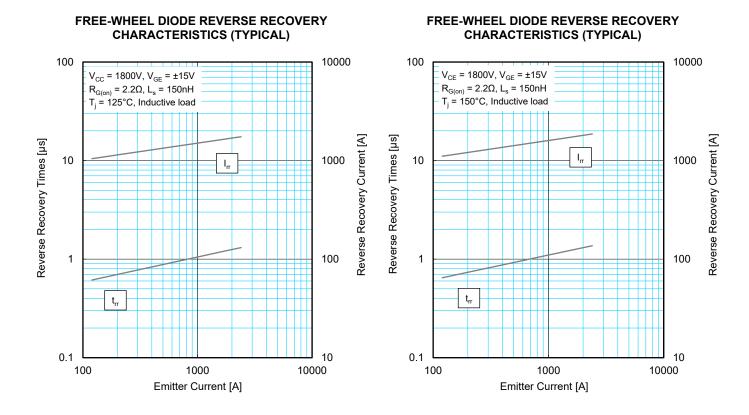
HALF-BRIDGE SWITCHING TIME

CHARACTERISTICS (TYPICAL)

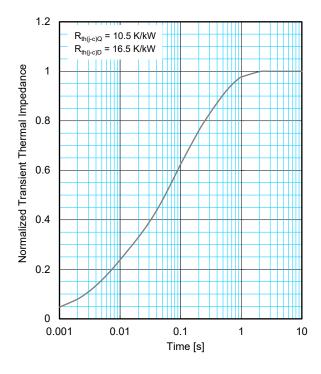
HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



100



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS

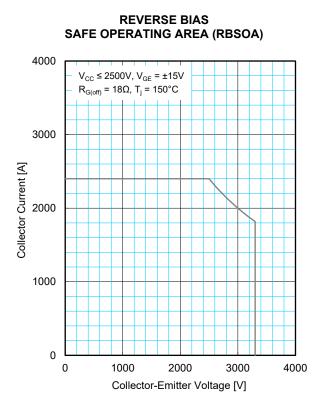


$Z_{th(j-c)}(t) = \sum_{i=1}^{n} R_{i} \left\{ 1 - \exp\left(-\frac{t}{\tau_{i}}\right) \right\}$

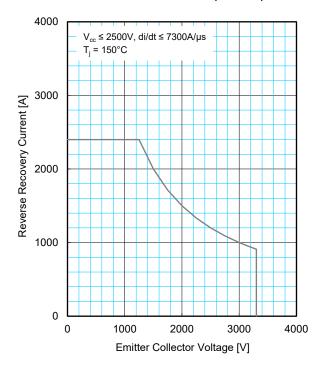
	1	2	3	4
Ri / Rth(j-c)	0.0096	0.1893	0.4044	0.3967
τ i [sec]	0.0001	0.0058	0.0602	0.3512

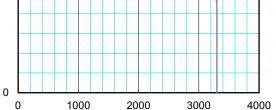
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PERFORMANCE CURVES



FREE-WHEEL DIODE REVERSE RECOVERY SAFE OPERATING AREA (RRSOA)





Collector-Emitter Voltage [V]

SHORT CIRCUIT SAFE OPERATING AREA (SCSOA)

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5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

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